



# DA2S00100L

Silicon epitaxial planar type

For band switching

■ Features

- Low forward dynamic resistance  $r_f$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

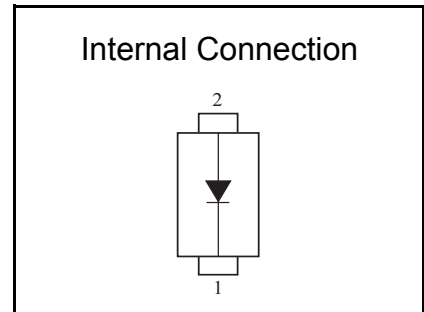
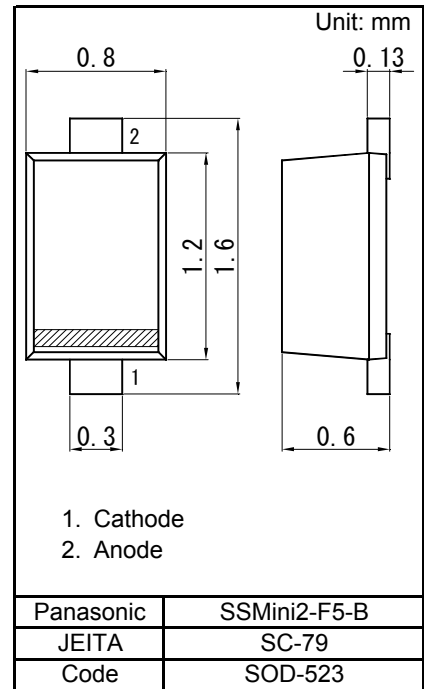
■ Marking Symbol: D1

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings  $T_a = 25\text{ }^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	40	V
Forward current	IF	100	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C





■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA		0.92	1.0	V
Reverse current	IR	VR = 40 V			100	nA
Diode capacitance	CD	VR = 6 V, f = 1 MHz		0.9	1.2	pF
Forward dynamic resistance *1	rf	IF = 2 mA, f = 100 MHz		0.65	0.85	Ω

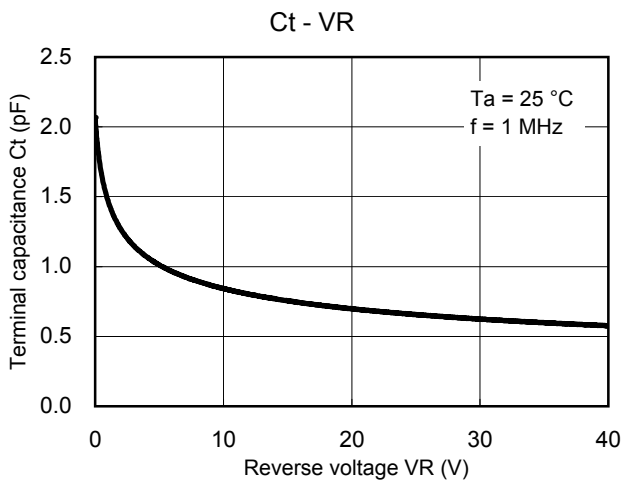
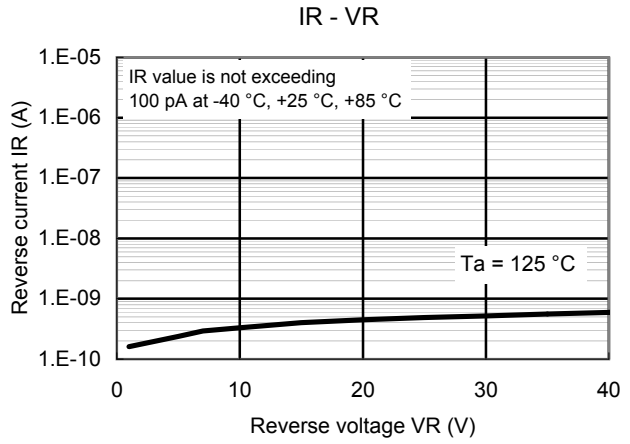
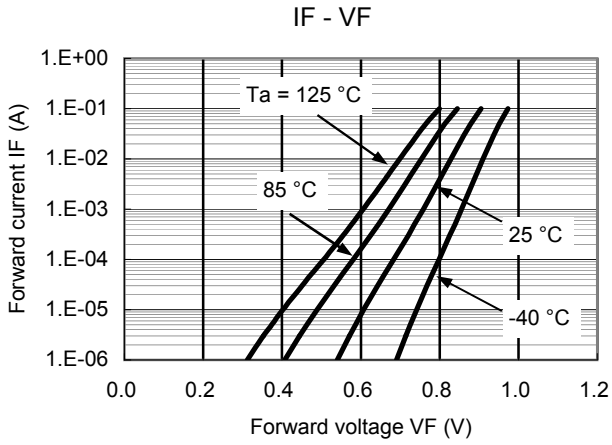
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. \*1 Measure YHP MODL 4191A RF IMPEDANCE ANALYZER

Standard frequency of input and output is 100MHz.



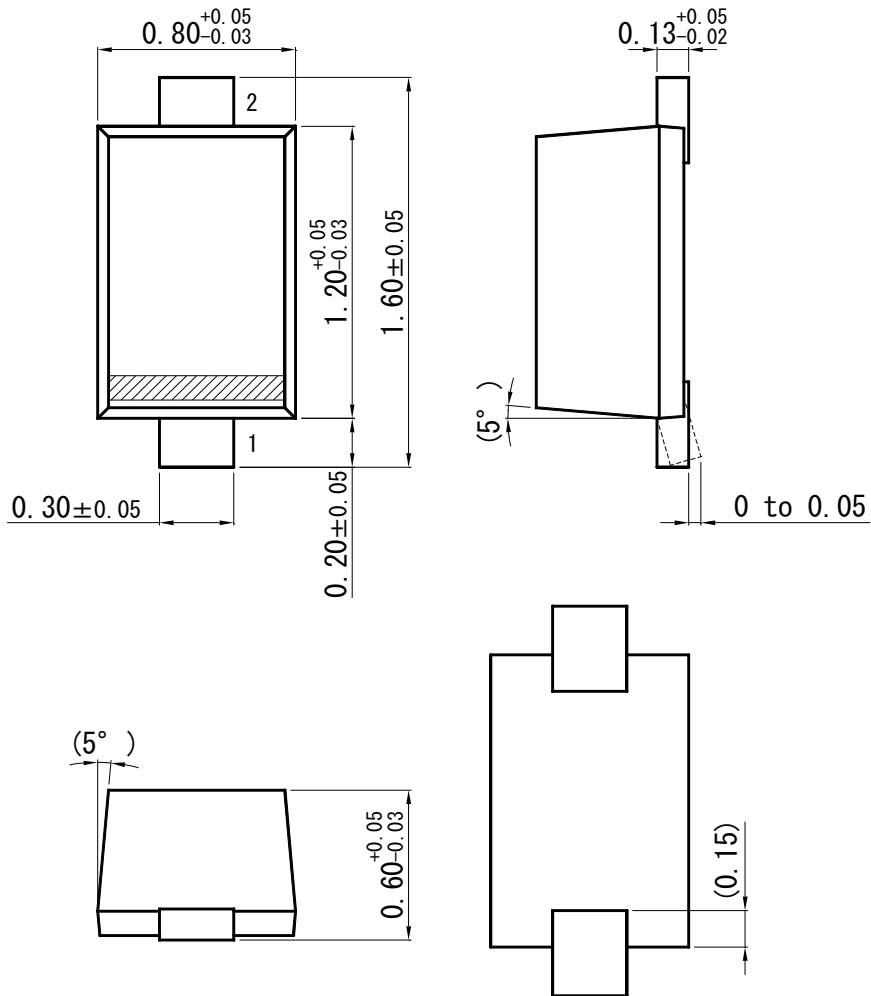
Technical Data ( reference )



**Panasonic**

SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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